Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

In the Claims:

Please amend the claims as follows:

- (currently amended) A connection between a pair of electrical components comprising:

 a male component having an array of spaced apart bumps;
 a female component having a matching array of spaced apart wells;
 bonding material substantially filling said wells; and
 wherein each of said bumps extends into the material in its matching well and bonds with

 said bonding material to form a connection to said female component.
- 2. (original) The connection of claim 1 wherein said bumps are gold stud bumps.
- 3. (original) The connection of claim 1 wherein said bonding material is solder.
- 4. (original) The connection of claim 1 wherein said components are alignment sensitive.
- 5. (cancelled).
- 6. (original) The connection of claim 3 wherein said male component or said female component is an electrical component.
- 7. (original) The connection of claim 3 wherein said solder is indium-based.
- 8. (currently amended) The connection of claim 6 wherein [one of] said electrical component is an integrated circuit chip.
- 9. (currently amended) The connection of claim 6 wherein [one of] said electrical component is a module access cable.

- 10. (currently amended) The connection of claim 6 wherein [one of] said electrical component is an interconnection circuit.
- 11. (currently amended) A method for connecting a pair of <u>electrical</u> components comprising the steps of:

providing an array of bumps on a male component; providing a matching array of wells in a female component;

filling said wells with bonding material;

aligning said male and female components and inserting said bumps <u>into the material</u> in said wells; and,

activating said bonding material to attach said female component to said male component.

- 12. (cancelled).
- 13. (original) A method for aligning a pair of components comprising the steps of: providing an array of bumps on a male component; providing a matching array of wells in a female component; filling said wells with bonding material; positioning said female and male components relative to one another and inserting said

bumps in said wells;
monitoring an alignment-sensitive performance parameter for the combined components;
optimizing said positioning by maximizing said performance parameter; and,

14. (new) A connection between a pair of components comprising:

bonding said bumps to said wells using said bonding material.

a male component having an array of bumps spaced apart less than 200 microns;

a female component having a matching array of wells spaced apart less than 200 microns;

bonding material in said wells; and

wherein each of said bumps extends into its matching well and bonds to said bonding material to form a connection to said female component.

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- 15. (new) A method for connecting a pair of electrical components comprising the steps of: providing an array of bumps on a male component; providing a matching array of wells in a female component; using a squeegee, filling said wells with bonding material; aligning said male and female components and inserting said bumps in said wells; and activating said bonding material to attach said female component to said male component.
- 16. (new) The method of claim 11 in which the said bump material is gold and said bonding material is solder.

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